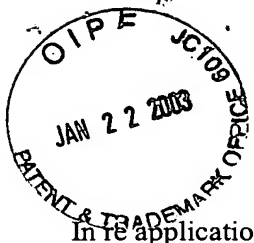


2826 #



PATENT APPLICATION
Do. No. 9903-045

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sang-Ho AHN and Se-Yong OH

Serial No. 10/008,704

Examiner: Tran, Tan N

Confirmation No. 8392

Filed: December 6, 2001

Group Art Unit: 2826

For: ULTRA-THIN SEMICONDUCTOR PACKAGE DEVICE AND METHOD
FOR MANUFACTURING THE SAME

RECEIVED
JAN 29 2003
TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents,
Washington, D.C. 20231

Responsive to the Office Action dated September 23, 2002, enclosed is an amendment in the above-identified application.

The fee has been calculated as shown below.

CLAIMS AS AMENDED					
For:	Number After Amendment	Previous Number	Extra	Rate	Additional Fee
Total Claims	92	53	39	x \$18 =	\$702.00
Independent Claims	8	5	3	x \$84 =	\$252.00
Extension of Time - 1 st					\$110.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$1064.00

*greater of twenty (20) or number for which fee has been paid

**greater of three (3) or number for which fee has been paid

- ☒ PTO Form 2038 authorizing credit card payment for the above-listed fees is enclosed.
☒ Any deficiency or overpayment should be charged or credited to deposit account number 13-1703.

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.



20575

PATENT TRADEMARK OFFICE

01/24/2003 HBIZUNES 00000028 10008704.

04 FC:1251

110.00 OP

Alan T. McCollom
Reg. No. 28,881

MARGER JOHNSON & McCOLLOM, P.C.
1030 SW Morrison Street
Portland, OR 97205
(503) 222-3613

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL BY AN ENVELOPE ADDRESSED TO:
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 1-17-03

[Signature]



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BOX NON FEE AMENDMENT
Assistant Commissioner for Patents
Washington, D.C. 20231

01/24/2003 MBIZUNES 00000028 10008704

01 FC:1806
02 FC:1202
03 FC:1201

180.00 BP
702.00 OP
252.00 OP

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JAN 29 2003
TECHNOLOGY CENTER 2826

#10/Ext (U)
B
2/3/03
Schmith

RESPONSE TO OFFICE ACTION

02/04/2003 ASMITH 00000002 131703 10008704
Responsive to the Office Action, dated September 23, 2002, please amend the
application as follows.
01 FC:1201 84.00 CH
02 FC:1202 360.00 CH

IN THE CLAIMS

A full set of pending claims, including any amendments or cancellations as of this response, is as follows:

1. An ultra-thin semiconductor package device comprising:
 - a lead frame comprising a die pad, a plurality of leads disposed around the die pad, and tie bars connected to and disposed around the die pad, wherein said die pad comprises a chip attaching part and a peripheral part surrounding the chip attaching part;
 - a semiconductor chip mounted to the die pad chip attaching part, said chip having a plurality of electrode pads, wherein the plurality of electrode pads are electrically interconnected to the leads; and wherein each of the leads comprises integrally connected inner leads and outer leads;
 - an encapsulant encapsulating the semiconductor chip to form a package body, wherein said inner leads are encapsulated by the encapsulant and said outer leads are external to the encapsulant; and
 - said chip attaching part having a first thickness and the inner leads having a second thickness greater than the first thickness.